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(54) **EMI REDUCTION DEVICE AND ASSEMBLY**

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(57) **ABSTRACT**

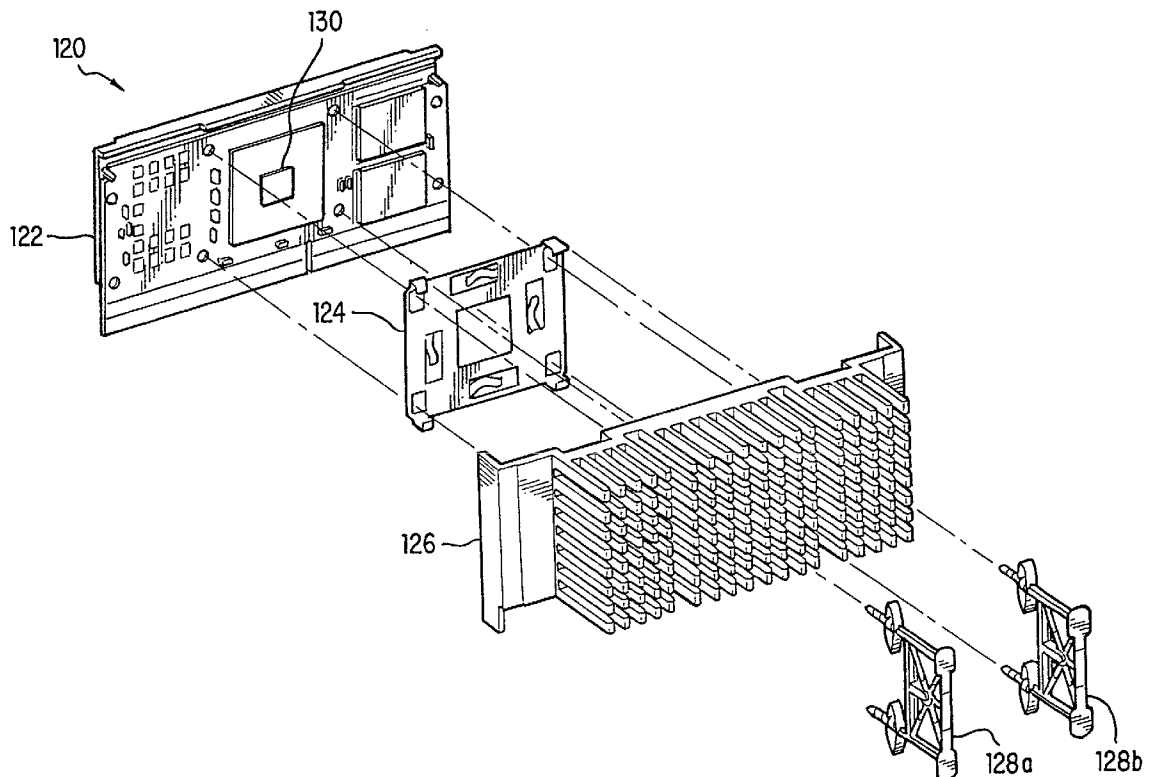
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Related U.S. Application Data

(63) Continuation of application No. 09/320,412, filed on May 26, 1999, now Pat. No. 6,219,239.

An EMI reduction device coupled between to a printed circuit board (PCB) assembly and a heat sink is herein disclosed. The PCB assembly includes a processor core that is the source of unintentional electromagnetic interference (EMI). The EMI reduction device is attached to a heat sink which is positioned over the processor core such that it capacitively couples emissions from the processor core to a grounding plane resident in the PCB assembly, thereby reducing the unintentional EMI. Simultaneously, the EMI reduction device is able to maintain thermal contact with the heat sink.



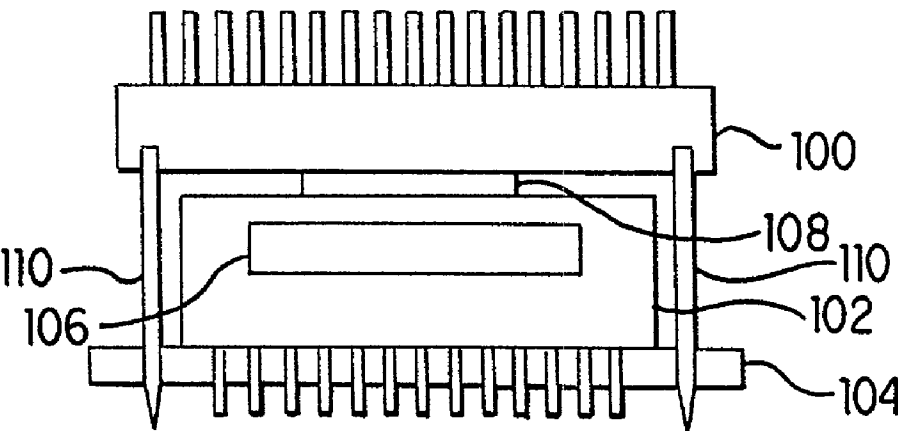


FIG. 1 PRIOR ART

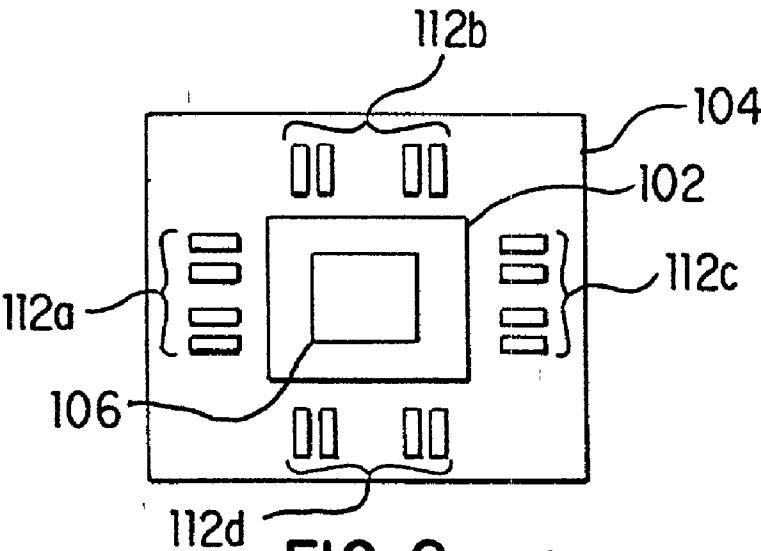
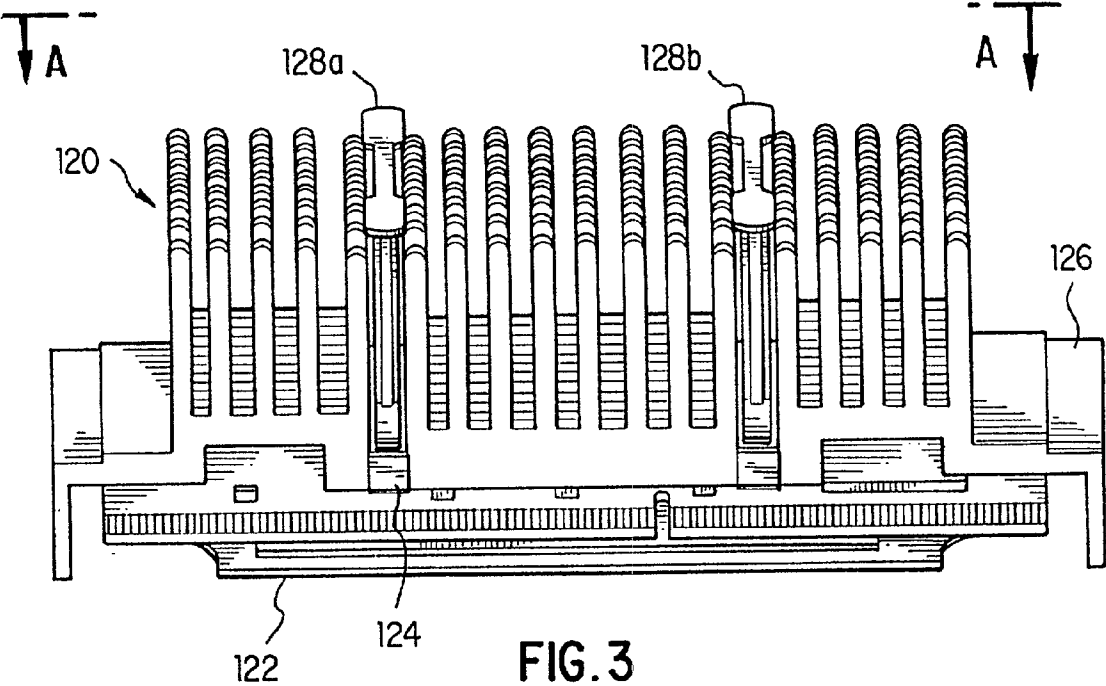


FIG. 2 PRIOR ART



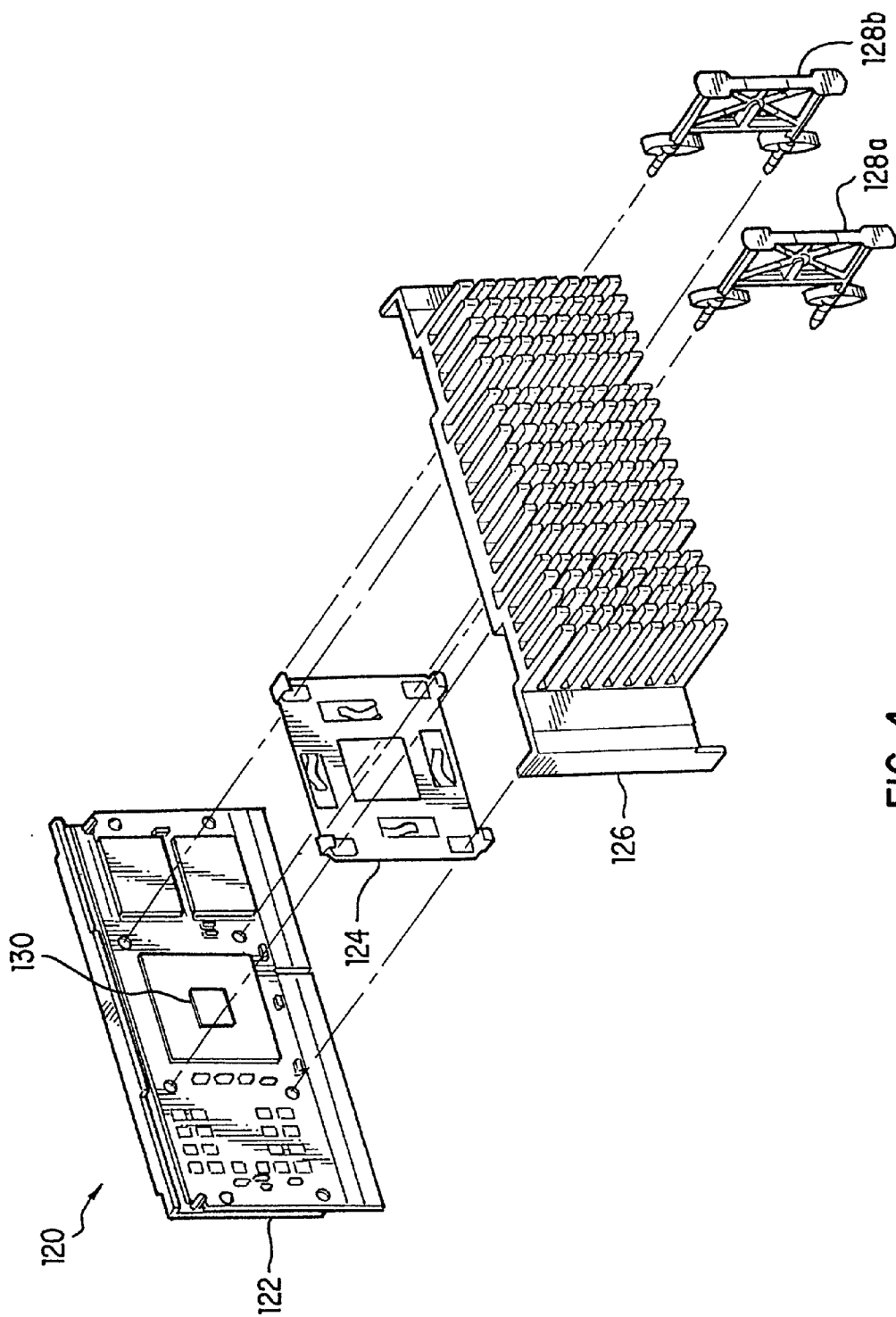


FIG. 4

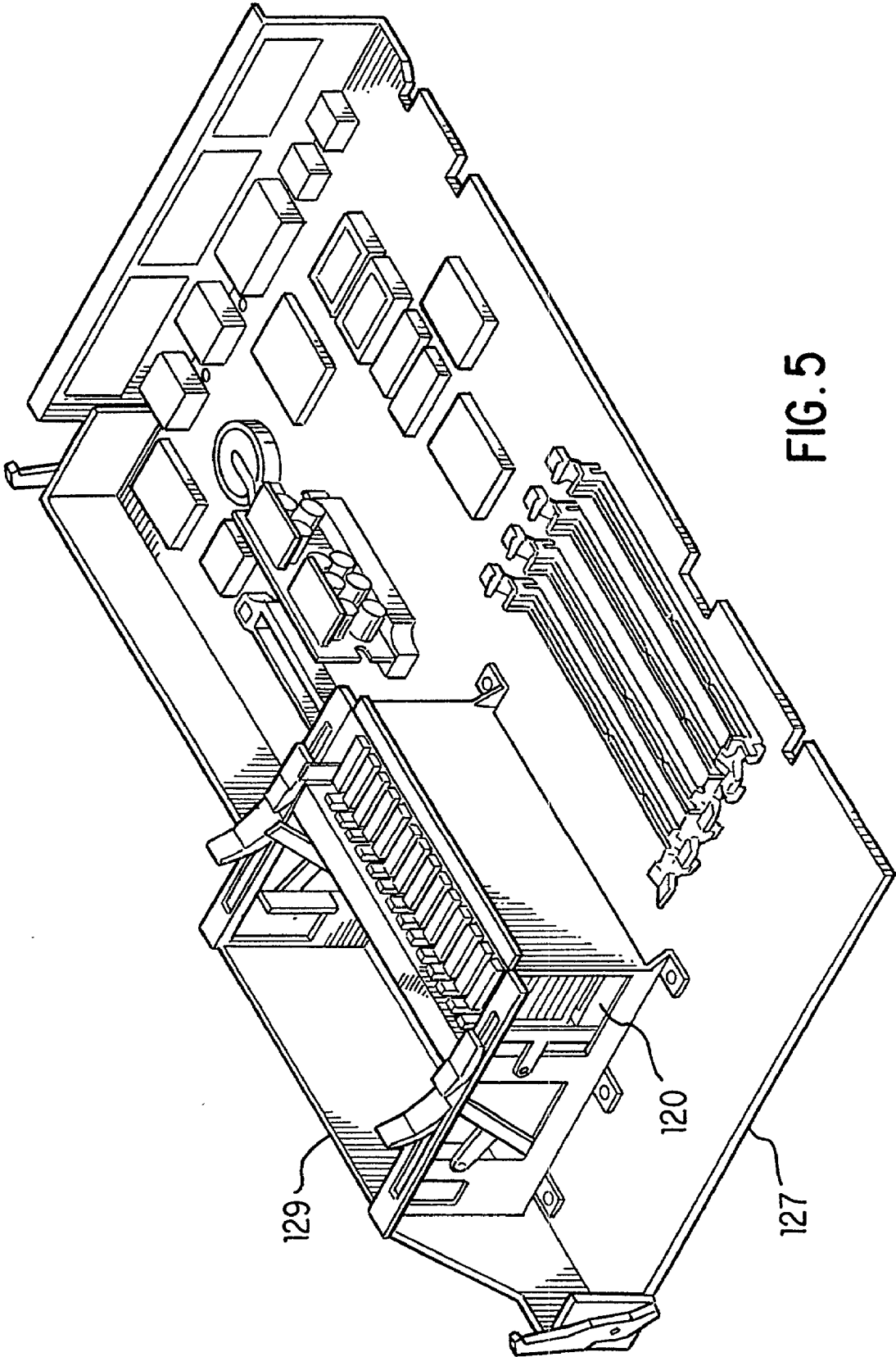
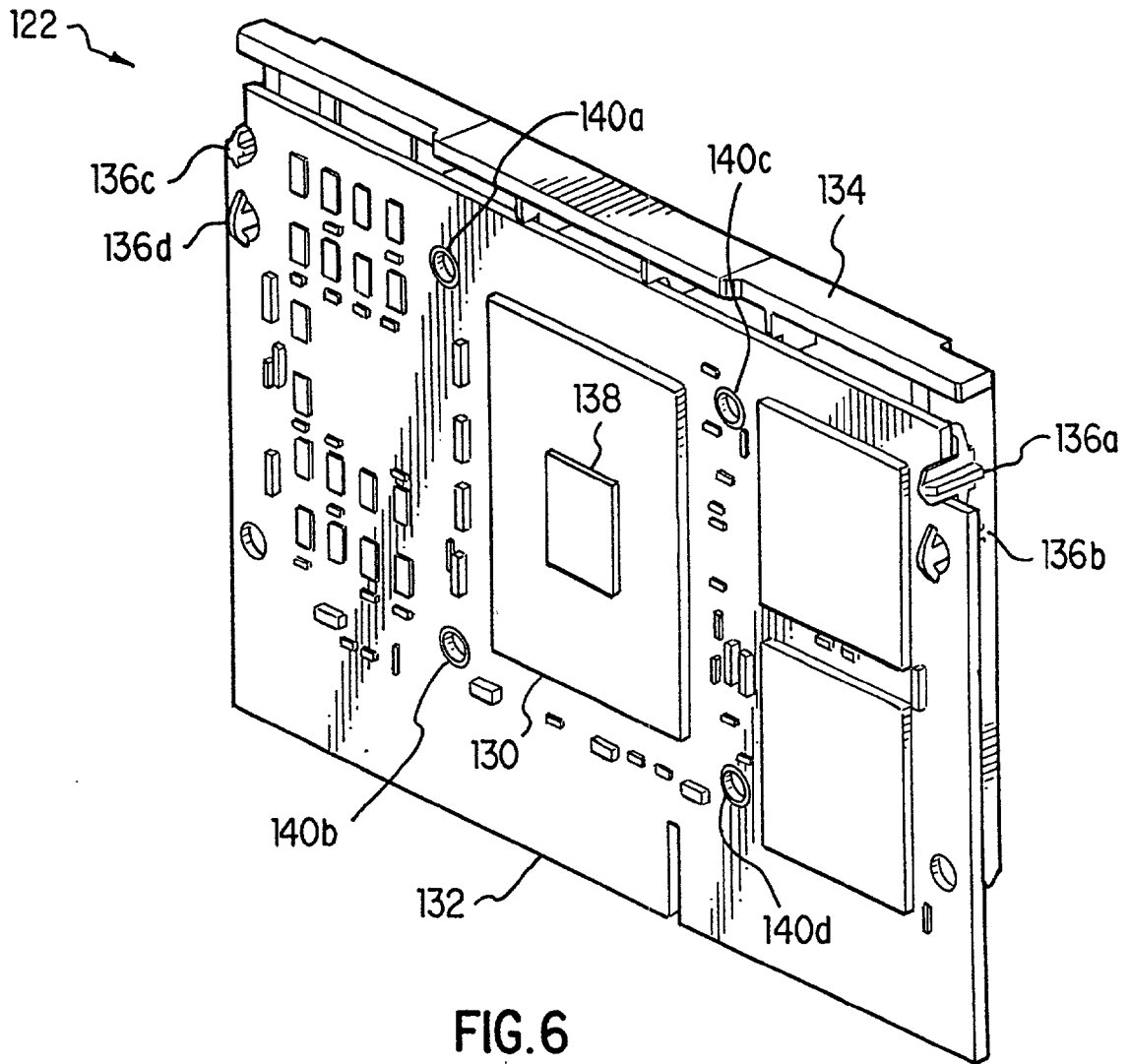
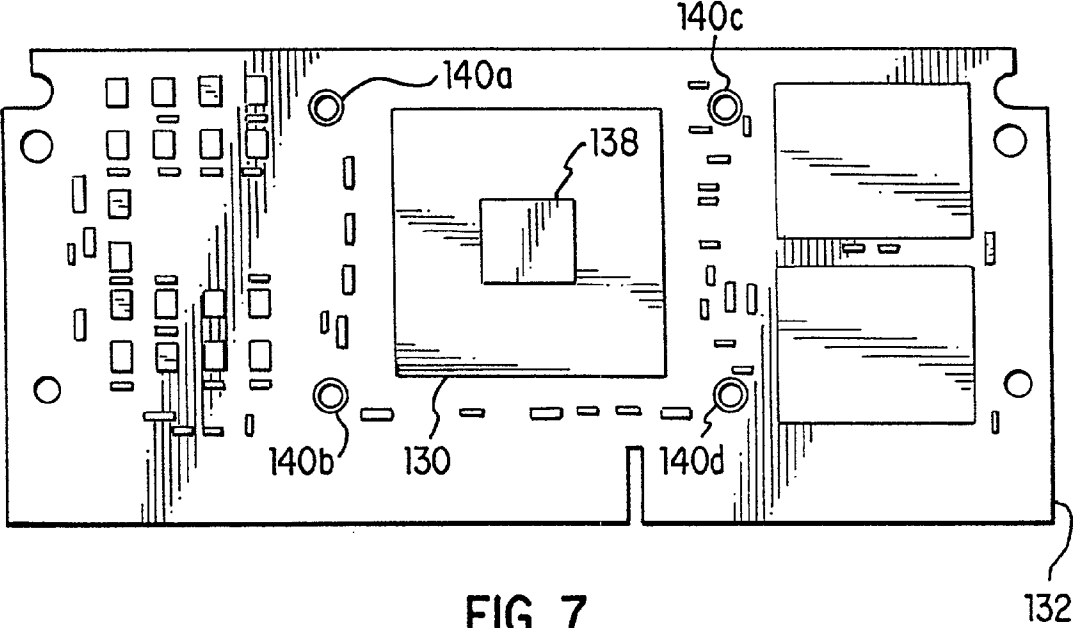


FIG. 5





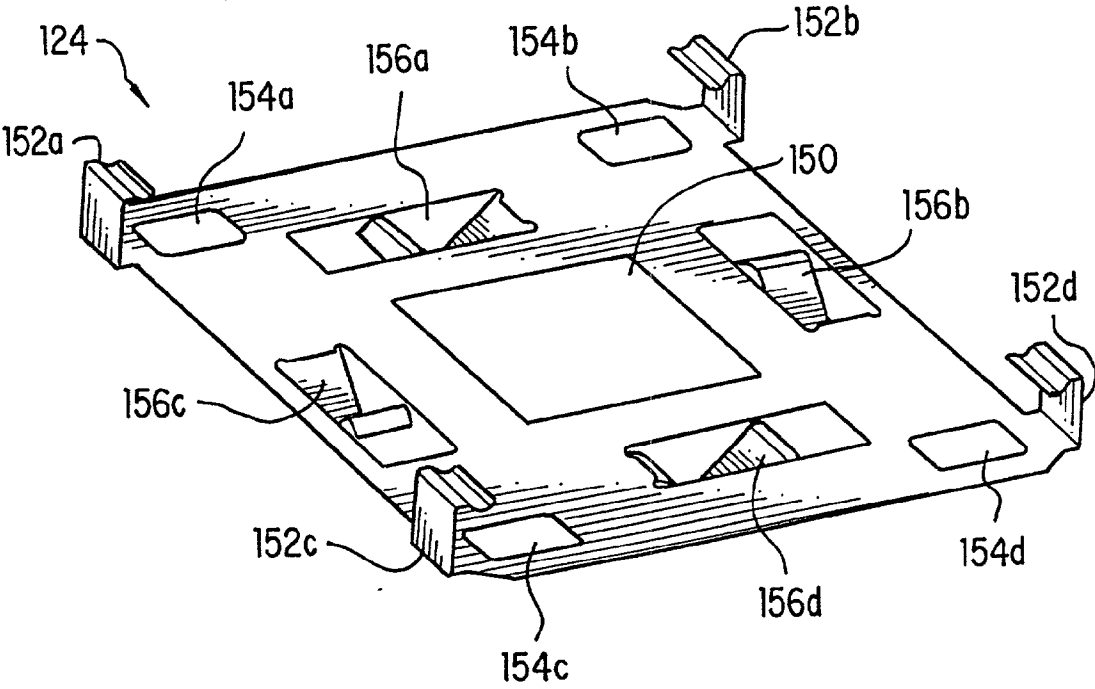


FIG. 8

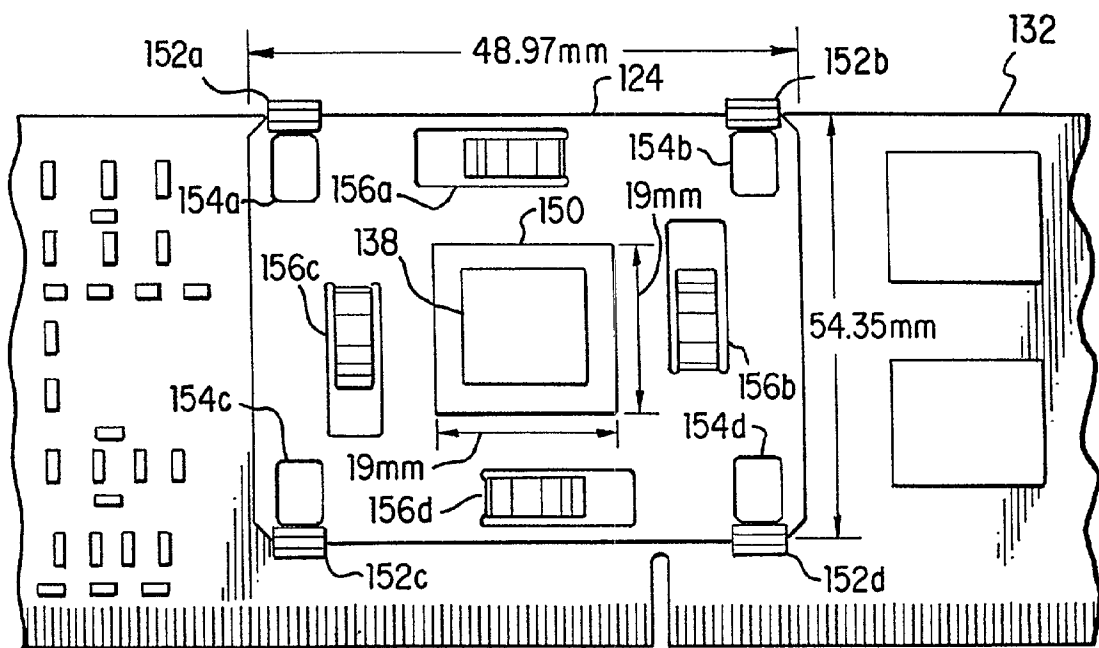


FIG. 9

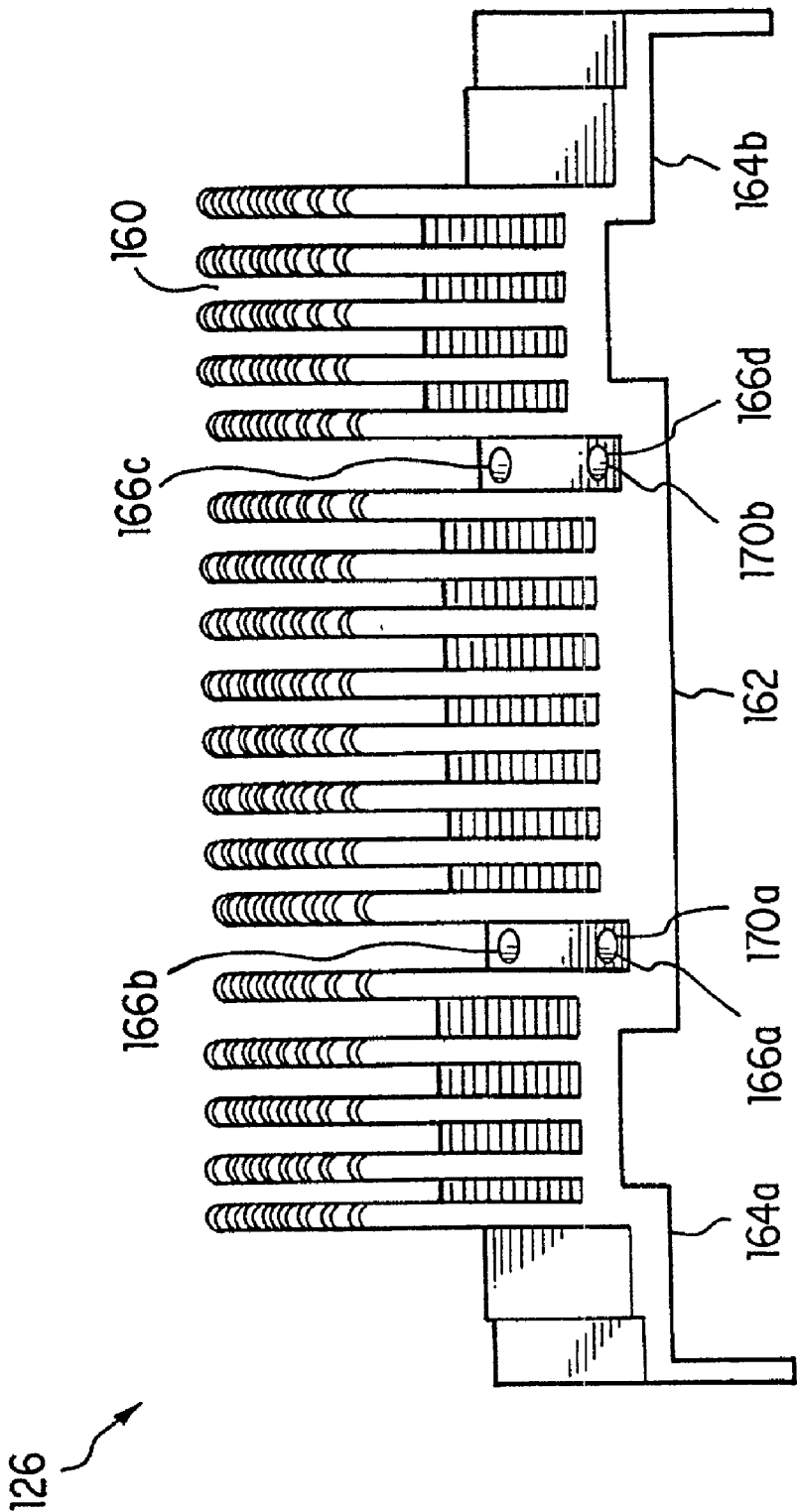


FIG. 10

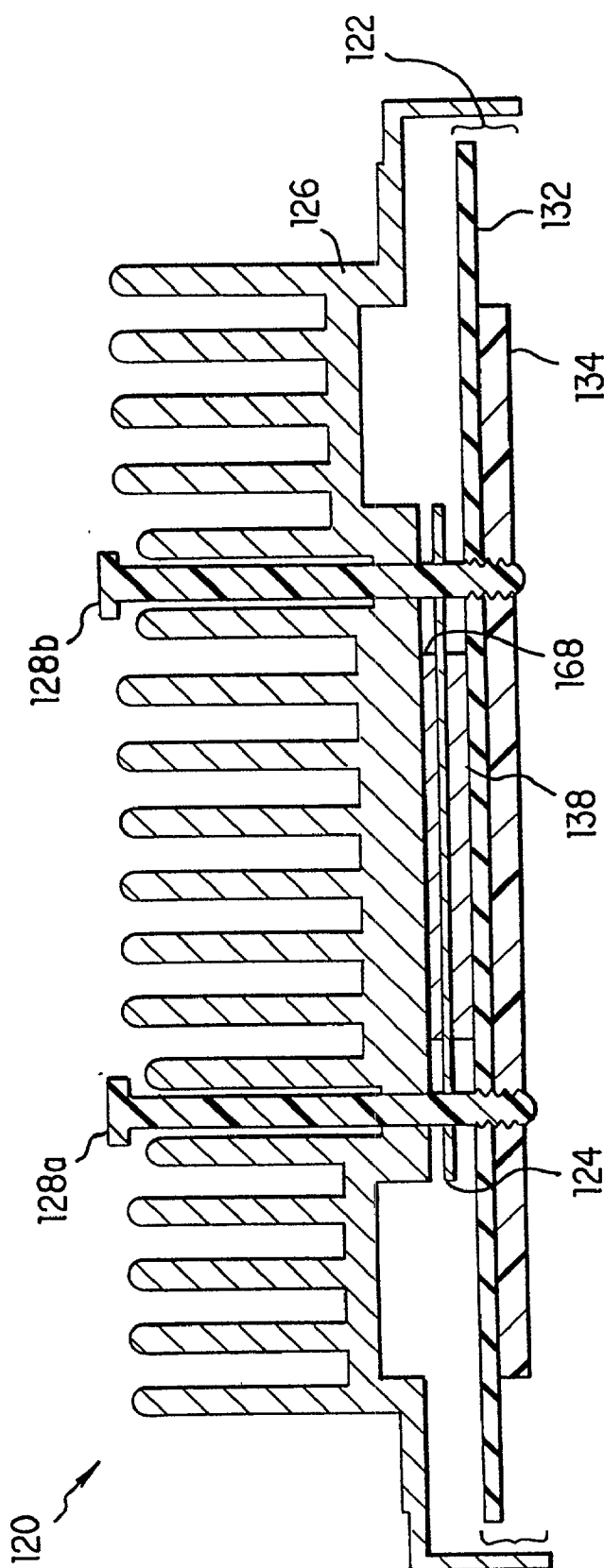


FIG. 11

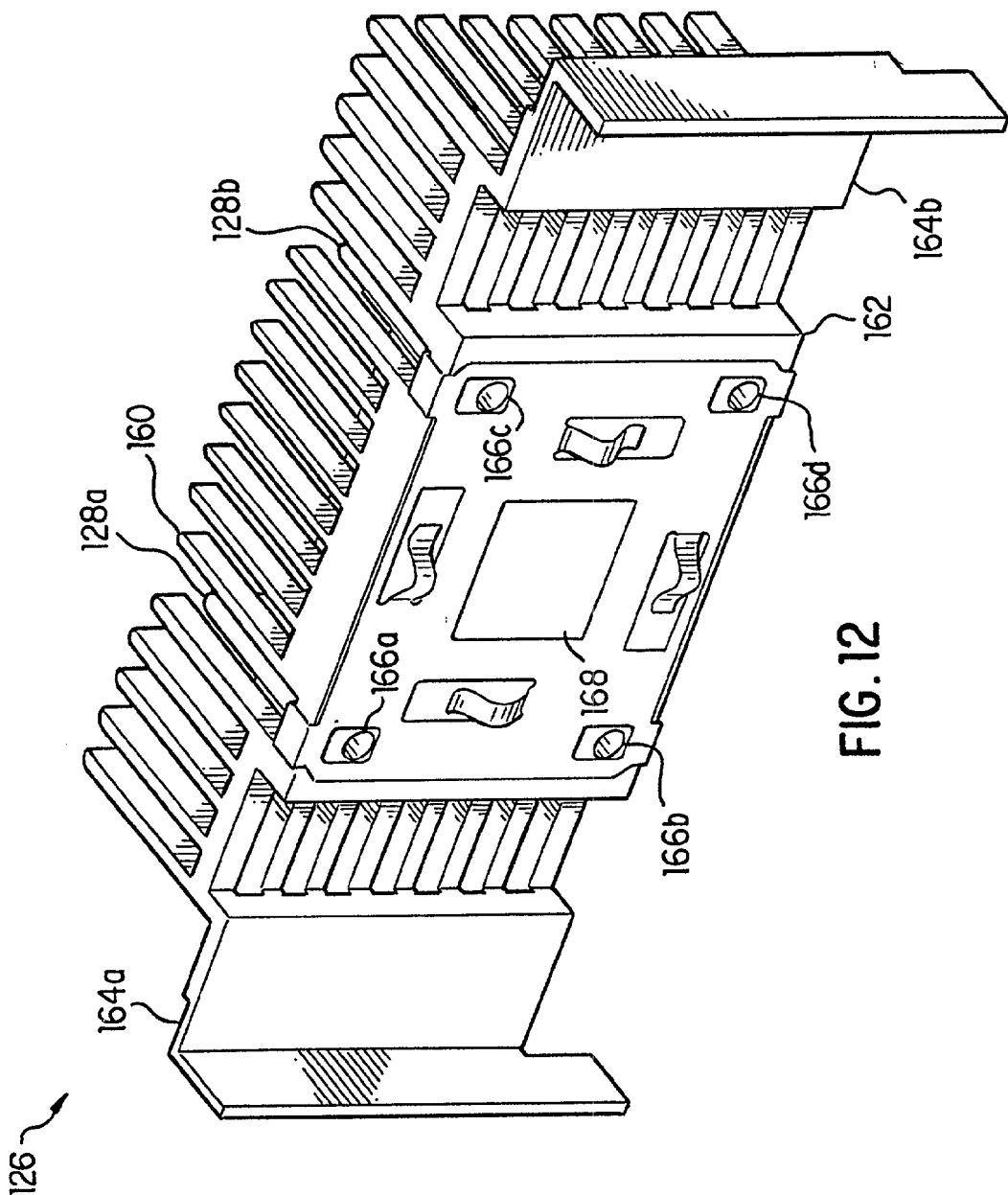


FIG. 12

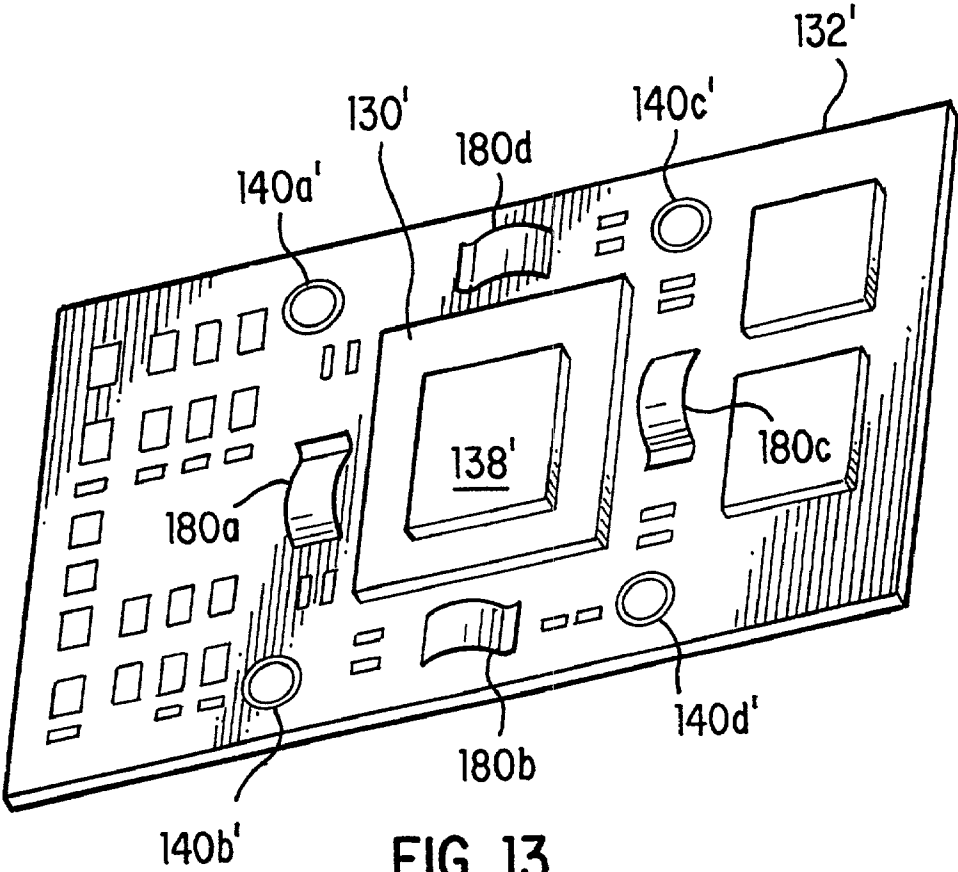


FIG. 13

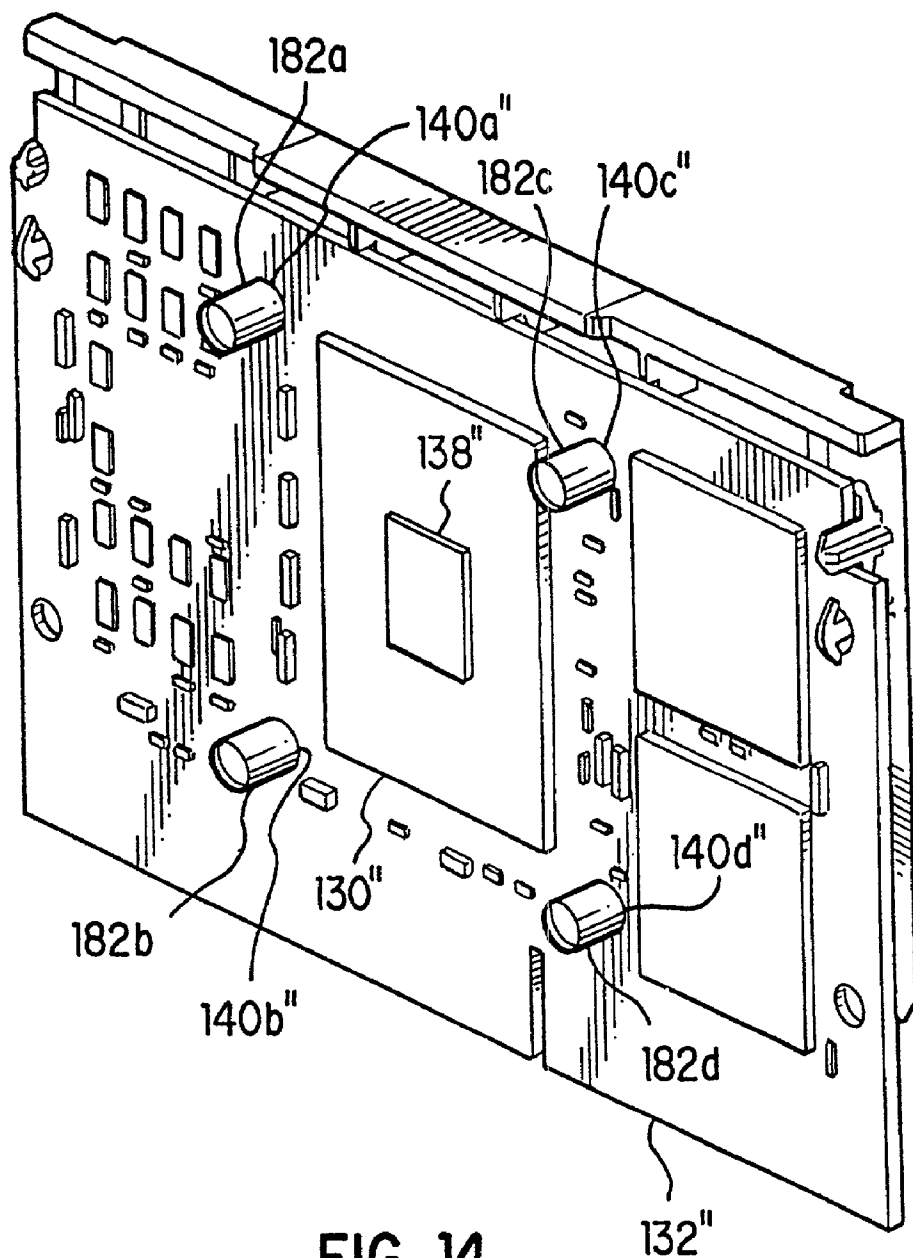


FIG. 14

EMI REDUCTION DEVICE AND ASSEMBLY

FIELD OF THE INVENTION

[0001] The present invention relates generally to electronic systems. More particularly, the invention relates to an electromagnetic interference (EMI) reduction device.

BACKGROUND OF THE INVENTION

[0002] A trend in the electronics industry is to generate smaller and faster electronic devices. As a result, these devices consume more power and hence, produce more heat. Excessive heat can cause significant damage to an electronic device thereby reducing its life. For this reason, various techniques are employed to eliminate or dissipate the heat generated from the electronic device. A heat sink is one such technique. A heat sink is thermally coupled to the electronic device and as such, allows the heat to flow from the electronic device through the heat sink to the surrounding open space.

[0003] In addition, the operation of these electronic devices is accompanied by the generation of electromagnetic radiation or energy. The emissions of the electromagnetic radiation can cause significant electronic interference or noise with other surrounding electronic circuitry. To reduce such disturbances, the source of these emissions is usually suppressed. However, the EMI suppression problem is further complicated when the electronic device is coupled to a heat sink. The heat sink acts as an antenna for the EMI energy thereby amplifying the EMI energy.

[0004] A common solution for suppressing EMI energy is to ground the heat sink. FIG. 1 illustrates an exemplary grounded heat sink. There is shown a heat sink 100 coupled to a grounded electronic device 102 that is mounted onto a printed circuit board (PCB) 104. In this example, the grounded electronic device 102 is a processor core having a silicon logic die 106. A thermal compound 108, such as a dielectric material, is placed between the heat sink 100 and the grounded electronic device 102 so that thermal contact is maintained and the heat generated by the device 102 is transferred to the heat sink 100.

[0005] Mounting fences 110 are positioned on four opposite sides of the PCB 104 in order to ground the heat sink 100. The mounting fences 110 are attached to the heat sink 100 and the PCB 104, which acts in this case as a ground plane. The mounting fences 110 provide a Faraday shield around the device 102 in order to shield the EMI energy generated from the clock circuitry internal to the processor 102 from damaging adjacent components and from releasing EMI energy outside of the heat sink 100.

[0006] Additional EMI suppression is provided by four sets of grounding pads 112a-112d on the PCB 104 that surround the processor 102, as shown in FIG. 2. The grounding pads 112 minimize or ground EMI noise generated by the switching of all the component pins under maximum capacitive load. Thus, the combination of the grounding pads and the grounded heat sink dissipates the heat from the processor core and grounds the EMI energy generated by the processor core.

[0007] As the internal clock speed of processors increase, these processors will require more extensive EMI reduction or grounding. In some cases, the grounded heat sink

approach may not be suitable to effectively eliminate the EMI emissions since this approach has a longer grounding path. As such, grounding may need to be performed closer to the silicon logic die in order to create a shorter grounding path that effectively shields the EMI energy emanating from the processor core.

[0008] Accordingly, there is a need for an EMI reduction technique that can minimize or eliminate EMI energy generated from a processor core closer to the source of the emissions and in such a manner that is cost efficient and easy to manufacture.

SUMMARY OF THE INVENTION

[0009] The present invention pertains to an EMI reduction device that is coupled between a printed circuit board (PCB) assembly and a heat sink. The PCB assembly includes a processor core that is the source of a large amount of electromagnetic interference. In a first embodiment, the EMI reduction device is fastened to a heat sink which is positioned over the processor core such that it capacitively couples the emissions from the processor while maintaining thermal contact with the heat sink.

[0010] In a first embodiment, the EMI reduction device has a electrically-conductive rectangular frame that includes a die aperture positioned in the center of the device, four mounting clip tabs, and four spring contact fingers. The die aperture allows the processor logic die to be in direct physical contact with the bottom surface of the heat sink thereby maintaining thermal contact between the processor logic die and the heat sink. The four mounting clip tabs are positioned on the outer periphery of the reduction device and are used to clip the EMI reduction device to the heat sink.

[0011] The spring contact fingers are located on each of the four sides of the processor. The spring contact fingers are the only portion of the EMI reduction device that maintains physical contact with the PCB assembly. This is to ensure that the EMI reduction device does not protrude directly onto the PCB assembly yet remains in close proximity to the processor. As such, the EMI reduction device is not in direct electrical contact with the PCB assembly. The EMI reduction device grounds the processor emissions by capacitively coupling them to the ground plane present in the PCB assembly.

[0012] A pair of heat sink retention clips is used to secure the heat sink to the PCB assembly. The heat sink retention clips are inserted through mounting holes on the heat sink in a downward direction through the mounting holes of the EMI clip and on the PCB assembly.

[0013] The placement of the EMI clip in close proximity with the processor is beneficial since it creates a shorter grounding path thereby effectively reducing the EMI energy emanating from the processor directly at the source. In addition, the EMI clip is able to accomplish this while maintaining thermal contact with the heat sink. Furthermore, performing the EMI reduction at the processor is more economical than incorporating an EMI reduction technique into a chassis assembly that houses the PCB assembly.

BRIEF DESCRIPTION OF THE DRAWINGS

[0014] For a better understanding of the nature and objects of the invention, reference should be made to the following

detailed description taken in conjunction with the accompanying drawings, in which:

[0015] FIG. 1 is a schematic view of a prior art grounded heat sink assembly for a printed circuit board;

[0016] FIG. 2 is a top plan view of the printed circuit board used in the grounded heat sink assembly shown in FIG. 1;

[0017] FIG. 3 is a perspective view of a processor module in accordance with a first embodiment of the present invention;

[0018] FIG. 4 is an exploded view of the components of the processor module shown in FIG. 3;

[0019] FIG. 5 illustrates the processor module positioned on a printed circuit board as part of computer system in accordance with the embodiments of the present invention;

[0020] FIG. 6 is a front perspective view of the printed circuit board assembly shown in FIGS. 3 and 4;

[0021] FIG. 7 is a top plan view of the printed circuit board shown in FIG. 6;

[0022] FIG. 8 is a perspective view of the bottom side of the EMI clip shown in FIGS. 3 and 4;

[0023] FIG. 9 is a top plan view of the EMI clip positioned onto the printed circuit board assembly in accordance with a first embodiment of the present invention;

[0024] FIG. 10 is a perspective view of the heat sink shown in FIGS. 3 and 4 in accordance with the embodiments of the present invention;

[0025] FIG. 11 is cross-sectional view of the processor module taken along plane AA shown in FIG. 3;

[0026] FIG. 12 is a rear perspective view of the heat sink with the EMI clip attached thereto in accordance with the first embodiment of the present invention;

[0027] FIG. 13 is an isometric view of a printed circuit board having spring fingers mounted onto the PCB assembly in accordance with a second embodiment of the present invention; and

[0028] FIG. 14 is an isometric view of a printed circuit board having spring washers in accordance with a third embodiment of the present invention.

[0029] Like reference numerals refer to corresponding parts throughout the several views of the drawings.

DETAILED DESCRIPTION OF THE INVENTION

[0030] FIGS. 3 and 4 depict a processor module 120 having a PCB assembly 122, an EMI clip or reduction device 124, a heat sink 126, and a pair of heat sink retention clips 128a-128b. The PCB assembly 122 includes a processor core 130. The EMI clip 124 is positioned onto the PCB assembly 122 surrounding the processor core 130 and is used to efficiently shield the EMI emissions generated from the processor core 130. The EMI clip 124 is removably mounted to the heat sink 126. The heat sink 126 is thermally coupled to the PCB assembly 122 and is used to transfer the heat from the electronic components to the heat sink 126. A

pair of heat sink retention clips 128 is used to fasten the heat sink 126 to the PCB assembly 122.

[0031] The processor module 120 can be removably mounted onto a motherboard or other type of circuit board. For example, as shown in FIG. 5, the processor module 120 is positioned onto a motherboard 127 through a processor retention assembly 129. The motherboard 127 can be part of a computer system, subsystem, or the like.

[0032] Preferably, the PCB assembly 122 is a Single Edge Contact Cartridge 2 (SECC2) manufactured by the Intel Corporation. The SECC2 supports "slot" type processors. A slot is a connector that is resident on a motherboard and which supports the Intel P6 microprocessor bus. Previously, microprocessors were mounted onto a motherboard through a socket. In a slot-type processor, the processor is placed on a PCB known as a single edge contact (SEC). The SEC has pins on an edge of the card which is inserted into a 242-pin slot on the motherboard. This pin construction is otherwise known as an edge finger connection.

[0033] A more detailed discussion of the SECC2 can be found in Intel Corporation, Single Edge Contact Connector 2 (S.E.C.C.2) Thermal Interface Material Functional Requirements, Order No: 244458-001, November 1998; Intel Corporation, Single Edge Contact Cartridge 2 (S.E.C.C.2) Heat Sink Attachment and Heat Sink Functional Requirements Order Number: 244456-001, Nov. 23, 1998; and Intel Corporation, S.E.C.C.2 Heat Sink Installation and Removal Process, Order Number 244454-001, December 1998 which are hereby incorporated by reference as background information.

[0034] FIG. 6 illustrates the SECC2 122. There is shown a printed circuit board 132 and a cover 134. The PCB 132 is preferably a substrate constructed of a multilayer plastic laminate, such as a plastic land grid array or organic land grid array processor core substrates. The substrate 132 has an edge finger connection. In addition, the substrate 132 includes a ground plane. The cover 134 is used to protect the PCB 132 and is removably mounted to the cover 134 through a set of snaps 136. However, it should be noted that the technology of the present invention is not constrained to the SECC2, to any particular circuit board, or to any particular circuit board layout.

[0035] FIG. 7 illustrates the PCB 132 in further detail. There is a processor core 130 that includes a silicon logic die 138. The PCB 132 includes four attachment holes 140a-140d through which the heat sink retention clips 128 are fit so that the heat sink can be attached to the PCB assembly 122. In addition, surrounding the logic die 138, there are other electronic components, such as but not limited to cache memory, resistors, capacitors, and the like. However, in this embodiment of the PCB 132, there are no grounding pads.

[0036] FIG. 8 illustrates the EMI clip 124. The EMI clip 124 has rectangular-shaped frame including a die aperture 150, four mounting clip tabs 152a-152d, four attachment holes 154a-154d, and four spring contact fingers 156a-156d. The die aperture 150 is of a rectangular shape and is located in the center of the EMI clip 124. The EMI clip 124 is positioned over the logic die 138 so that the die aperture 150 allows the logic die 138 to be in direct physical contact with the surface of the heat sink 126.

[0037] The four mounting clip tabs 152a-152d are used to attach the EMI clip 124 to the heat sink 126. The mounting

clip tabs **152a-152d** are located on the outer periphery of the EMI clip **124** and are situated in each corner of the top side of the EMI clip **124**.

[0038] The mounting holes **154a-154d** are located on the surface of the top side of the EMI clip **124** and each mounting hole **154** is located at a particular corner of the EMI clip **124**. Each of the four mounting holes **154a-154d** are aligned with a respective mounting hole **140** on the PCB **132** and with a respective mounting hole on the heat sink. The retention clips **128** are inserted through the mounting holes **166** on the heat sink **126** in a downward direction through the mounting holes **154** on the EMI clip **124** through the mounting holes **140** on the PCB **132**.

[0039] The four spring contact fingers **156a-156d** are situated on the bottom side of the EMI clip **124** and allow the EMI clip **124** to maintain physical contact on four sides of the processor core **130**. The contact fingers **156** are the only portion of the EMI clip **124** that is in physical contact with the PCB **132**. The spring fingers **156** ensure that the frame of the EMI clip **124** does not protrude directly onto any of the components of the PCB **132**. Direct contact with the processor substrate **132** would damage the electronic components positioned under the EMI clip **124**. As such, each of the spring contact fingers **156** is positioned on the PCB **132** in an area where there are no electronic components.

[0040] The shape, size and dimension of the EMI clip **124** is tailored for the particular processor substrate **132** to which the clip **124** is coupled. FIG. 9 illustrates the placement of the EMI clip **124** onto a SECC2 **122**. For this embodiment, the EMI clip **124** is approximately 48.97 mm by 54.35 mm. The die aperture **150** is 19 mm by 18 mm and is constructed such that there is a 6 mm distance between the outer edge of the processor aperture to the outer edge of the processor logic die. It should be noted that the present invention is not constrained to an EMI clip **124** having the particular shape, size and dimensions described herein and one skilled in the art can easily modify the design of the EMI clip **124** to suit other PCBs or the like.

[0041] The electromagnetic bandwidth of the processor core can extend to include multiple times the advertised processor clock speed. In the case of an Intel Pentium II processor with an internal clock speed of 500 MHz, the EMI bandwidth can extend to 2500 MHz or more. The EMI clip **124** reduces portions of that bandwidth with varying shielding effectiveness and can vary depending on the mechanical dimensions of the EMI clip **124**. Another modifier to EMI reduction is the mechanical pressure that exists both on the heat sink **126** and on the processor core **130**. The higher the pressure the more effective the capacitive coupling becomes and hence the EMI reduction.

[0042] Preferably, the EMI clip **124** is constructed of thin steel sheet metal. However, the present invention is not constrained to any particular type of metal and can be constructed of any material, such as but not limited to stainless steel, beryllium copper, phosphor bronze, hardened steel, spring steel, and the like.

[0043] Referring to FIG. 12, the bottom side of the heat sink **126**, that side which touches the PCB **132**, is coated with a dielectric layer that ensures that the EMI clip **124** does not short the electronic components mounted on the surface of the PCB **132**. An example of such a dielectric

coating is powder paint, in particular, the epoxy power coatings based on epoxy resins.

[0044] The placement of the EMI clip **124** over the processor core **130** and in the manner described above is effective in reducing the EMI emissions from the processor core **130**. Although, the EMI clip **124** is not in direct electrical contact with the processor core **130**, its close proximity to the processor core **130** capacitively couples these emissions to the ground plane of the substrate **132** and through a shorter grounding path. As a result, the emissions are minimized or eliminated directly at the processor core **130**.

[0045] FIGS. 10 and 11 illustrates the heat sink **126**. The heat sink **126** has a number of fins **160**, a base portion **162**, and two skirts **164a-164b**. The fins **160** project outwardly and upwardly from the base portion **162**. The base portion **162** extends over and covers the processor core **130** thereby providing the maximum amount of thermal contact area between the processor core **130** and the heat sink **126**. The two skirts **164a-164b** extend laterally and downwardly from the base portion **162** and extends over and covers opposite sides of the PCB assembly **122**.

[0046] The fins **160** are eliminated where the heat sink retention clips **128** are positioned (see FIGS. 3 and 4) into two grooves situated on the top surface of the base portion of the heat sink **126**. The grooves include mounting holes **166** that enable the heat sink retention clips **128** to fit through the top surface of the base portion **162**. The retention clips **128** are inserted through the mounting holes **166** on the heat sink **126** in a downward direction through the mounting holes **154** on the EMI clip **124** through the mounting holes **140** on the PCB **132**.

[0047] The heat sink retention clips **128** are made from a flexible material that is non-electrically conductive, such as plastic. The heat sink retention clips **128** are secured at one end in any appropriate manner, and in the present example by barbed ties. Preferably, the heat sink retention clips **128** are those heat sink retention clips designed for the SECC2 and which are manufactured by ITW Fastex.

[0048] FIG. 12 illustrates the bottom side of the base portion **162** of the heat sink **126**. There is shown the EMI clip **124** mounted to the base portion **162** of the heat sink **126**. Each mounting clip **152** is fitted over onto a corresponding groove **170** on the base portion of the heat sink **126**.

[0049] The heat sink **126** is made of aluminum that is chromate conversion coated and is electrically conductive. A thermal compound **168**, such as a dielectric layer, is placed on the bottom side of the base portion **162** of the heat sink **126**. This dielectric layer is used to provide high dielectric capacity and to provide a high thermal conductivity between the processor logic die **138** and the heat sink **126**. An example of such a compound is MCM-STRATE® manufactured by Power Devices, Inc. However, the present invention is not constrained to any particular type of material and other materials having the same properties can also be used.

[0050] The foregoing description, for purposes of explanation, used specific nomenclature to provide a thorough understanding of the invention. However, it will be apparent to one skilled in the art that the specific details are not

required in order to practice the invention. In other instances, well known circuits and devices are shown in order to avoid unnecessary distraction from the underlying invention. Thus, the foregoing descriptions of specific embodiments of the present invention are presented for purposes of illustration and description. They are not intended to be exhaustive or to limit the invention to the precise forms disclosed, obviously many modifications and variations are possible in view of the above teachings. The embodiments were chosen and described in order to best explain the principles of the invention and its practical applications, to thereby enable others skilled in the art to best utilize the invention and various embodiments with various modifications as are suited to the particular use contemplated. It is intended that the scope of the invention be defined by the following claims and their equivalents.

[0051] In particular, one skilled in the art can alter the EMI clip described above to include additional spring fingers in order to provide more capacitive contacts between the EMI clip and the substrate. In another alternate embodiment, the EMI clip can be used in conjunction with grounding pads that are positioned on the substrate. In yet another embodiment, the EMI clip can be made an integral part of the heat sink and not a separate device. Furthermore, the EMI clip can be made without the dielectric coating on the bottom surface thereby making electrical contact with the PCB. Alternatively, the EMI clip can be applied to a processor that is mounted directly onto a motherboard and is not constrained to edge finger connection devices.

[0052] FIG. 13 illustrates a second embodiment of the present invention. In this embodiment, there is no EMI clip 124 rather spring fingers 180a-180d mounted directly onto the printed circuit board 132'. Preferably, a spring finger 180 is mounted on each side surrounding the processor core 130'. As shown in FIG. 13, there are four spring fingers 180a-180d mounted directly onto the circuit board 132'. However, the number of spring fingers 180 and their position of the circuit board 132 is not a limitation of this embodiment.

[0053] A heat sink is mounted directly over the circuit board 132' and coupled with retention clips in the manner described above. The bottom surface of the heat sink will be in direct physical contact with the processor die 138' and the top surface of the spring fingers 180. As such, the emissions from the processor die 138' are capacitively coupled to the ground plane in the circuit board 132' and suppressed directly at the source of the emissions.

[0054] FIG. 14 illustrates a third embodiment of the present invention. In this embodiment, the ground plane of the circuit board 132" is extended to and through the mounting holes 140a"-140d" on the circuit board 132". A spring washer 182a-182d is mounted in each mounting hole 140a"-140d". A heat sink is mounted over the top surface of the circuit board 132".

[0055] The spring washers 182 are formed of an electrically conductive material, such as but not limited to thin sheet steel metal and are shaped as a compression coil. The spring washers 182 serve to ground the emissions from the processor core 130" while ensuring that the placement of the heat sink on top of the circuit board 132" does not damage the processor core 130" and the electronic components mounted thereon.

[0056] Each spring washer 182 has a hollow core that is wide enough to allow a retention clip to fit through it thereby

allowing the heat sink to be fastened to the circuit board 132" in the manner described above. When the heat sink is fastened to the circuit board 132", the spring washers 182 are compressed by the weight of the heat sink and the bottom surface of the heat sink is in direct physical contact with the processor die 138" and the top surface of the spring washers 182. As such, the emissions from the processor die 138" are grounded to the ground plane in the circuit board 132" and suppressed directly at the source of the emissions.

In the claims:

1. An electronic assembly apparatus, comprising:

a circuit board having a top surface and a bottom surface, the circuit board including an electronic device emanating electromagnetic emissions;

an EMI reduction device that is coupled to the circuit board, the EMI reduction device is positioned around the outer periphery of the electronic device, the EMI reduction device touches the circuit board at contact points that surround the electronic device, the EMI reduction device has no physical contact with the electronic device; and

a thermal dissipation device that is coupled to the EMI reduction device and the circuit board, the thermal dissipation device is positioned over the top surface of the circuit board;

wherein the thermal dissipation device dissipates heat generated from the circuit board;

wherein the EMI reduction device reduces electromagnetic emissions generated from the electronic device.

2. The apparatus of claim 1,

the EMI reduction device including at least one mounting clip for attaching the EMI reduction device to the thermal dissipation device.

3. The apparatus of claim 1,

the EMI reduction device including a plurality of spring fingers that surround the electronic device and maintain physical contact with the circuit board.

4. The apparatus of claim 1,

the EMI reduction device including an aperture that is positioned over the electronic device;

wherein the aperture enables the electronic device to maintain thermal contact with the thermal dissipation device.

5. The apparatus of claim 1,

the thermal dissipation device having a top surface and a bottom surface, the bottom surface including a thermal compound;

wherein the thermal compound is coupled to the electronic device.

6. The apparatus of claim 1,

the EMI reduction device having a top surface and a bottom surface, the bottom surface having a dielectric layer.

7. An EMI reduction device for use with an electronic device mounted on a circuit board, comprising:

a frame that is coupled to the circuit board, the frame surrounds peripheral portions of the electronic device,

the frame is not in physical contact with the electronic device, the frame having a top surface and a bottom surface; and

a plurality of spring fingers that are coupled to the circuit board, the spring fingers are positioned onto the circuit board at points that surround the electronic device.

8. The apparatus of claim 7, comprising:

an aperture that surrounds the electronic device;

wherein the aperture enables the electronic device to maintain thermal contact with a thermal dissipation device.

9. The apparatus of claim 7, comprising:

a fastener that is coupled to a thermal dissipation device;

wherein the fastener enables the EMI reduction device to be detachably mounted to a thermal dissipation device.

10. The apparatus of claim 7,

wherein the electronic device is a processor.

11. The apparatus of claim 7,

wherein the bottom surface of the frame is non-electrically conductive.

12. The apparatus of claim 7,

wherein the top surface of the frame is electrically conductive.

13. A method for reducing EMI emissions emanating from an electronic device having a ground plane, said method comprising the steps of:

surrounding the outer periphery of the electronic device with a frame that has no direct physical contact with the electronic device;

contacting the frame to the ground plane at contact points that surround the electronic device; and

capacitively coupling the EMI emissions from the electronic device to the ground plane.

14. The method of claim 13, comprising the steps of:

placing a thermal dissipation device over the electronic device; and

dissipating heat generated from the electronic device through the thermal dissipation device.

15. The method of claim 14, comprising the step of:

attaching the frame to the thermal dissipation device.

* * * * *